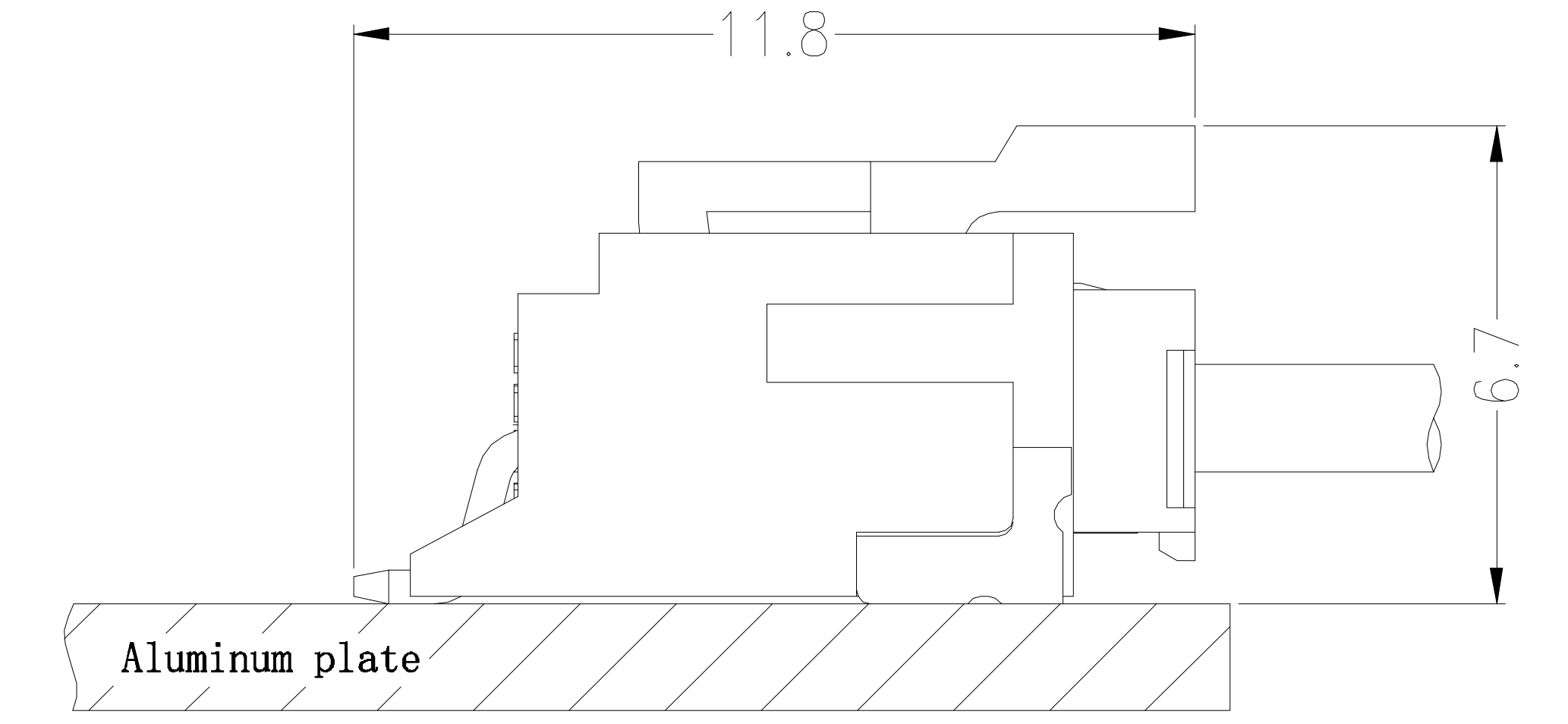
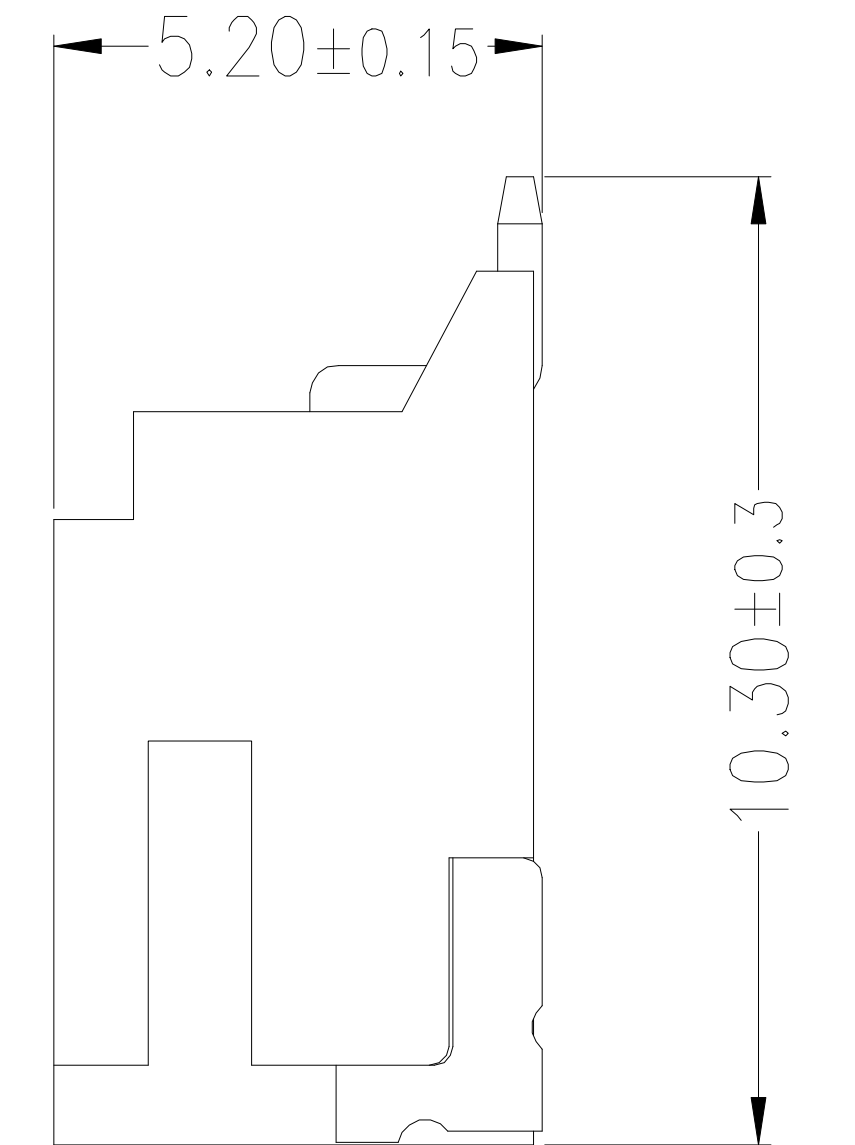
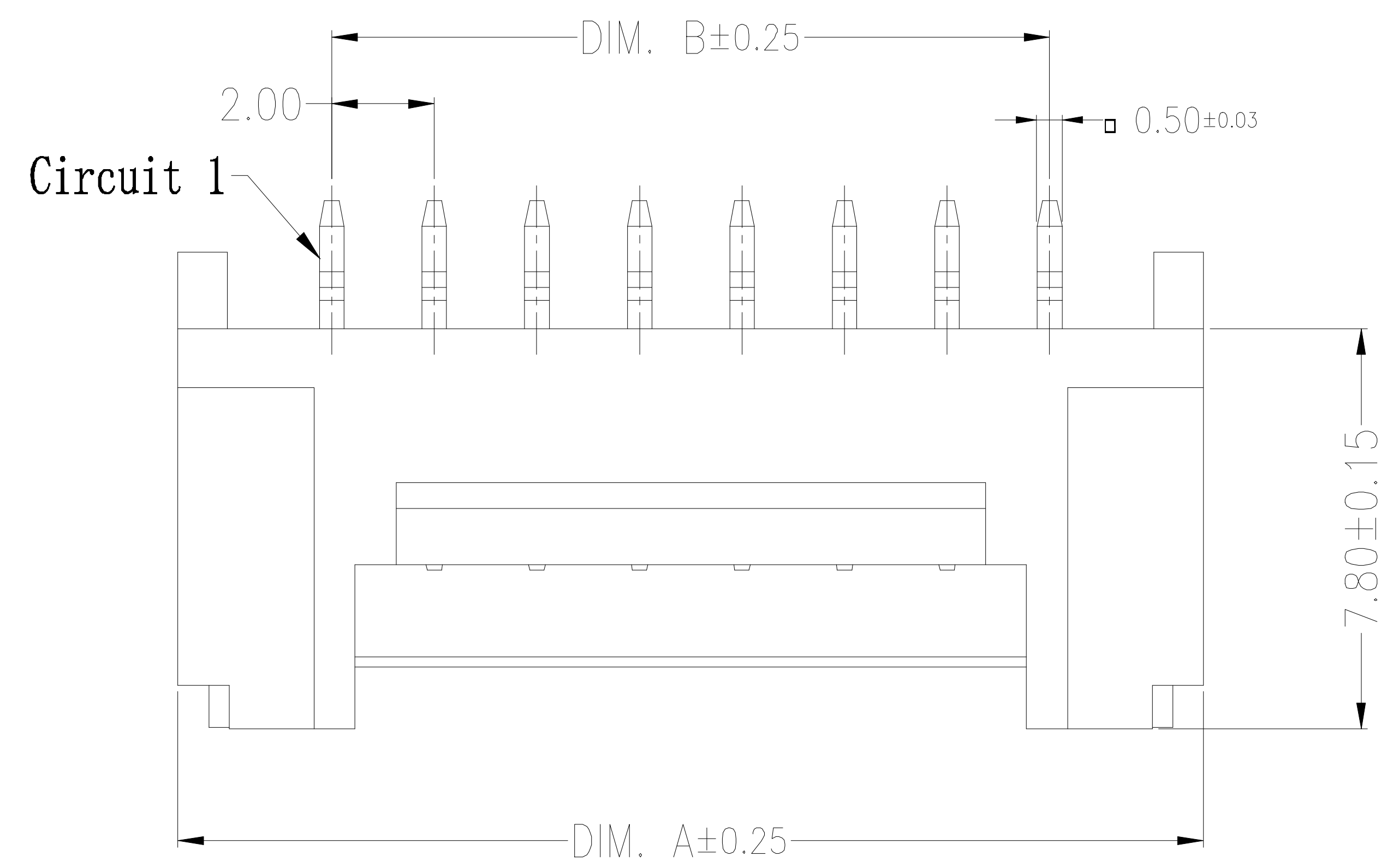
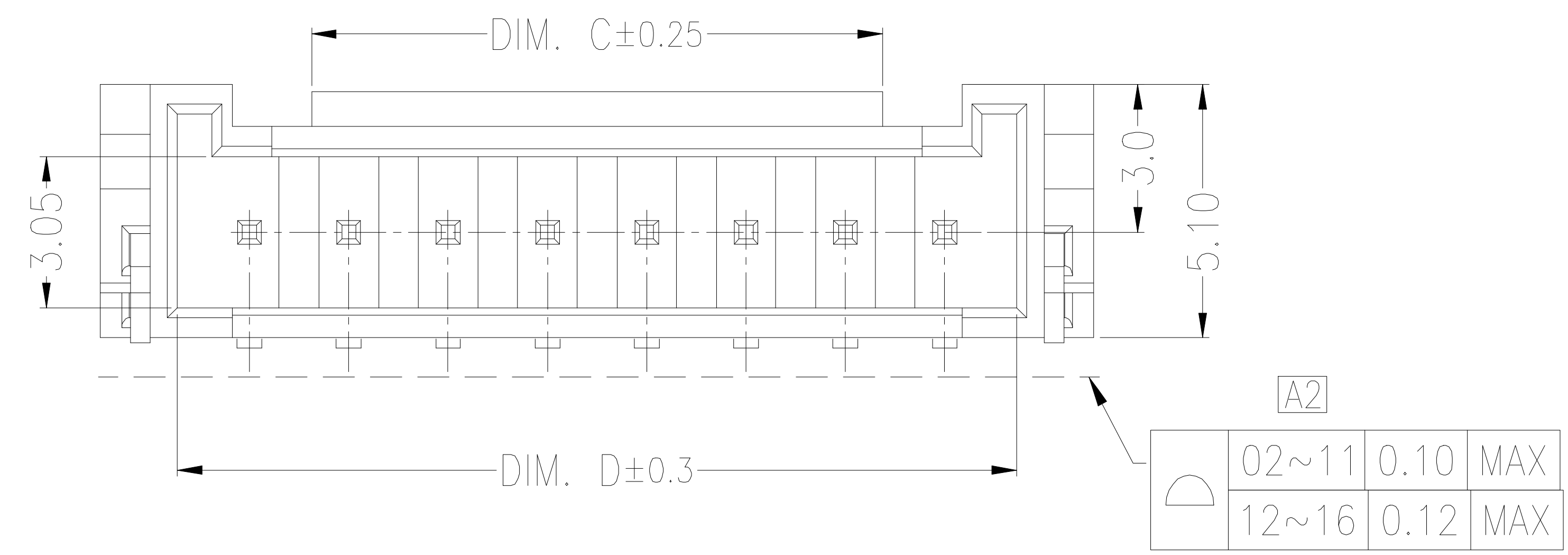


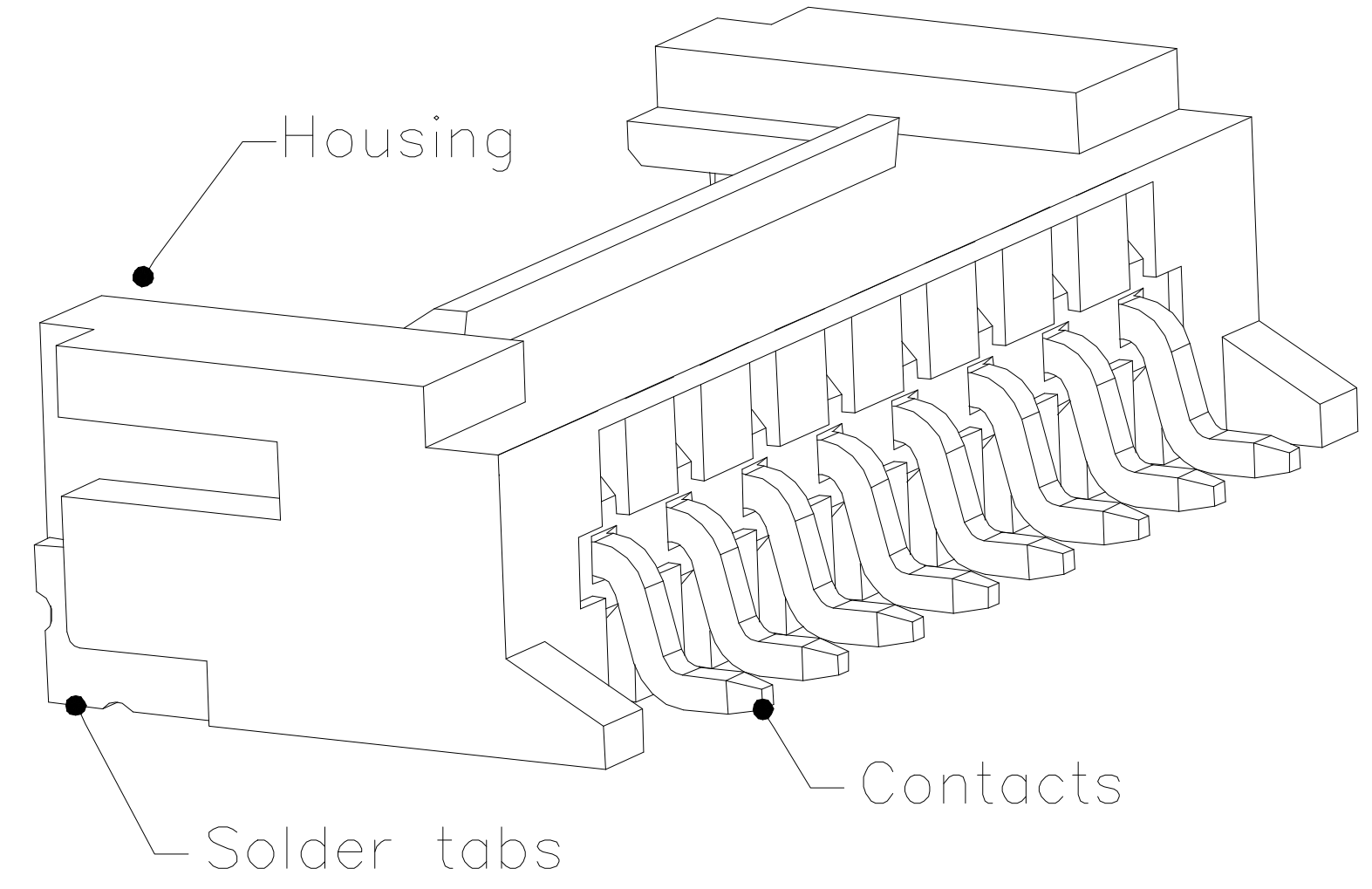
REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		



Assembly Layout



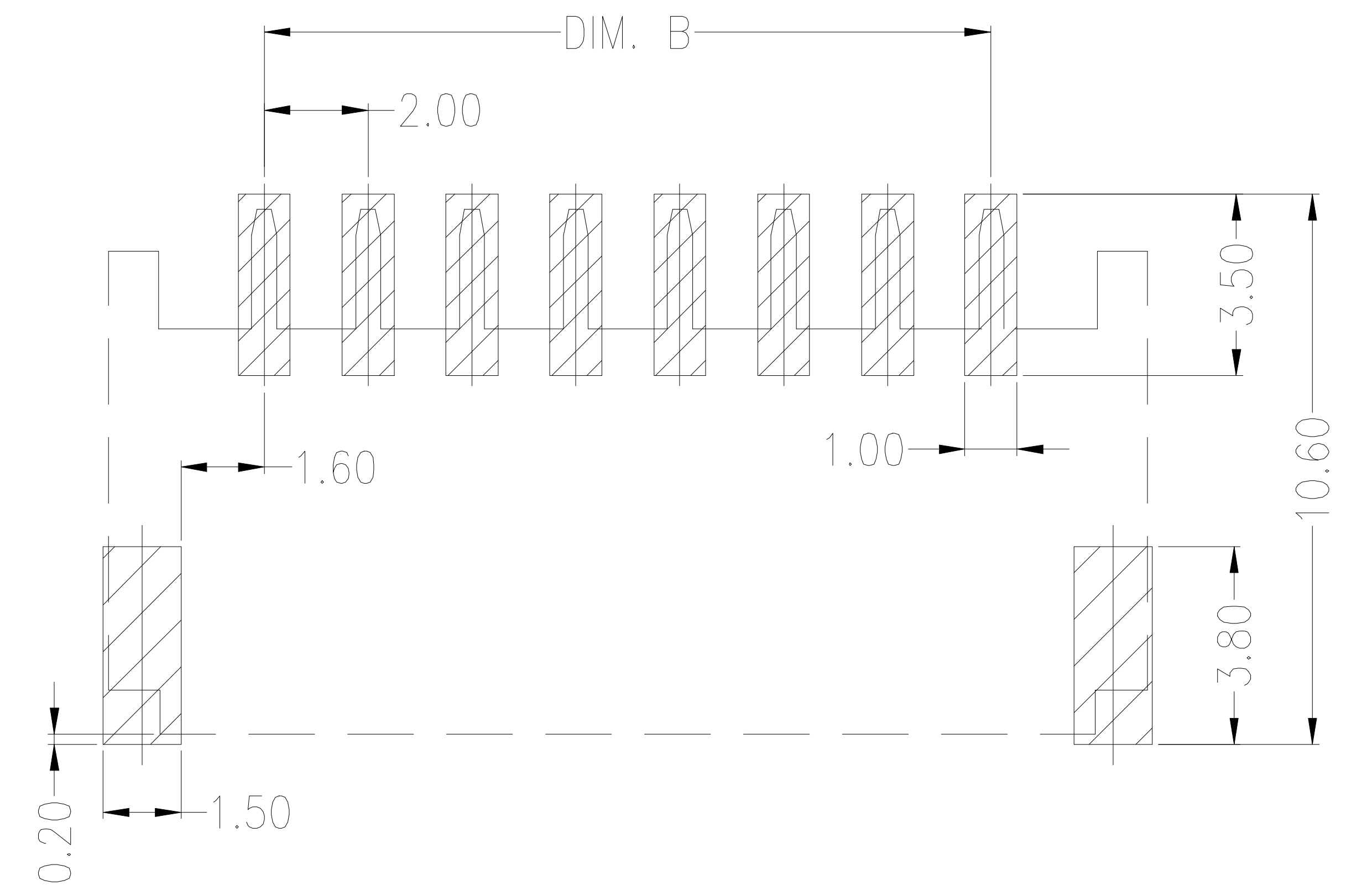
3D VIEWS



Circuits	Dimensions (mm)			
	DIM. A	DIM. B	DIM. C	DIM. D
02	8.00	2.00	2.70	4.75
03	10.00	4.00	3.20	6.75
04	12.00	6.00	3.50	8.90
05	14.00	8.00	5.50	10.90
06	16.00	10.00	7.50	12.90
07	18.00	12.00	9.50	14.90
08	20.00	14.00	11.50	16.90
09	22.00	16.00	13.50	18.90
10	24.00	18.00	15.50	20.90
11	26.00	20.00	15.50	22.90
12	28.00	22.00	15.50	24.90
13	30.00	24.00	15.50	26.90
14	32.00	26.00	15.50	28.90
15	34.00	28.00	15.50	30.90
16	36.00	30.00	15.50	32.90

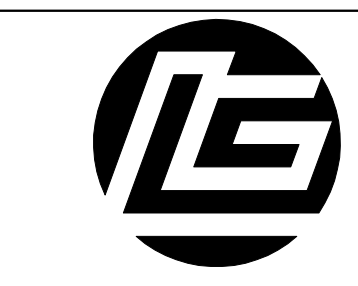
Specifications:

- Contact resistance: $\leq 20m\Omega$
- Insulation resistance: $\geq 1000M\Omega$
- Rated voltage: 250V AC DC
- Rated current: 2.0A AC DC
- Withstand voltage: 1000V AC/minute
- Temperature range: $-40^{\circ}C \sim +105^{\circ}C$
- Housing: LCP/PA6T/PA9T, UL94V-0 (Natural, Black)
- Contacts: Brass/Sn
- Solder tabs: Brass/Sn



SUGGESTED PCB LAYOUT

DESIGN:	Xiping Huang		
CHECK:	Ke Tian		
APPROVED:	Youquan Xu		
DIM	TOL	DIM	TOL
X.	± 0.25	X°	$\pm 3.0^{\circ}$
X.X	± 0.20	X.X°	
X.XX	± 0.15	X.XX°	
X.XXX		X.XXX°	



广东国连电子有限公司
GUANGDONG GUOLIAN ELECTRONICS CO., LTD

TITLE:	HY2.0卧贴				
PART NO.	HY2.0-NAWB-R				
REV.	A	SCALE:	N/A	UNIT:	mm
SHEET:	1/1				